

**CLAIMS**

1. A method of removing an organic light-emitting material from defined areas of a substrate comprising the steps of arranging a shadow mask to overlie the organic material other than in the defined areas, and applying a beam of ions to the defined areas through the mask.
2. A method according to claim 1, wherein the organic light-emitting material is polymeric.  
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3. A method according to claim 1 or 2, wherein at least one of the mask and the substrate has recesses in its surface facing the other of the mask and the substrate.
- 15 4. A method according to claim 1, 2 or 3, wherein the ions are chemically reactive with the organic material to be etched.
5. A method according to any preceding claim, wherein the ions are ions of a normally inert gas.  
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6. A method according to claim 5, wherein the ions are Argon ions.
7. A method according to any preceding claim, wherein the step of applying the beam of ions is carried out in a chamber having dimensions, at  
25 a pressure at which the mean free path of the ions is greater than or equivalent to the chamber dimensions.
8. A method according to any preceding claim, wherein the step of applying the beam of ions is carried out at a pressure less than  $5 \times 10^{-4}$  mbar.  
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9. A method according to any preceding claim, wherein the organic material is formed from an organic layer of an array of organic light emitting diodes on the substrate.

5 10. A method according to claim 8, wherein the organic material to be removed covers a bond pad region of the substrate.

11. A method according to claim 9 or 10, comprising removal of organic material from at least one organic light emitting diode pixel of the array of  
10 organic light emitting diode pixels.

12. A method according to any preceding claim, further comprising using the beam of ions to remove a layer of electrically conducting polymeric material in the defined areas.